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# United States Patent [19]

Suzuki

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## [54] MICROWAVE PLASMA PROCESSING APPARATUS AND METHOD THEREFOR

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906

### [56] References Cited

#### U.S. PATENT DOCUMENTS

4,741,800	5/1988	Yamazaki	156/643
4,776,918	10/1988	Otsubo et al.	156/345
5,024,716	6/1991	Sato	156/345
5,134,965	8/1992	Tokuda et al.	118/723
5,359,177	10/1994	Taki et al.	219/121.43
5,487,875	1/1996	Suzuki	422/186.05
5,538,699	7/1996	Suzuki	422/186.29
5,646,489	7/1997	Takehi et al.	315/111.21

### FOREIGN PATENT DOCUMENTS

5-345982 12/1993 Japan.

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### [57] ABSTRACT

For generating uniform high-density plasma over a large area with a low power thereby achieving high-quality plasma process at a high speed even at a low temperature, there is provided a microwave plasma processing apparatus comprising a plasma generation chamber having a periphery separated from the ambient air by a dielectric member, microwave introduction means utilizing an endless annular wave guide tube provided around the plasma generation chamber and provided with plural slots, a processing chamber connected to the plasma generation chamber, support means for a substrate to be processed provided in the processing chamber, gas introduction means for the plasma generation chamber and the processing chamber, and evacuation means for the plasma generation chamber and the processing chamber, wherein the circumferential length  $L_g$  of the endless annular wave guide tube, the wavelength  $\lambda_g$  of the microwave in the endless annular wave guide tube, the circumferential length  $L_s$  of the dielectric member and the wavelength  $\lambda_s$  of the surface wave propagating in the dielectric material substantially satisfy a relationship:

$$L_s/\lambda_s = (2n+1)L_g/\lambda_g$$

wherein n is 0 or a natural number.

59 Claims, 9 Drawing Sheets

